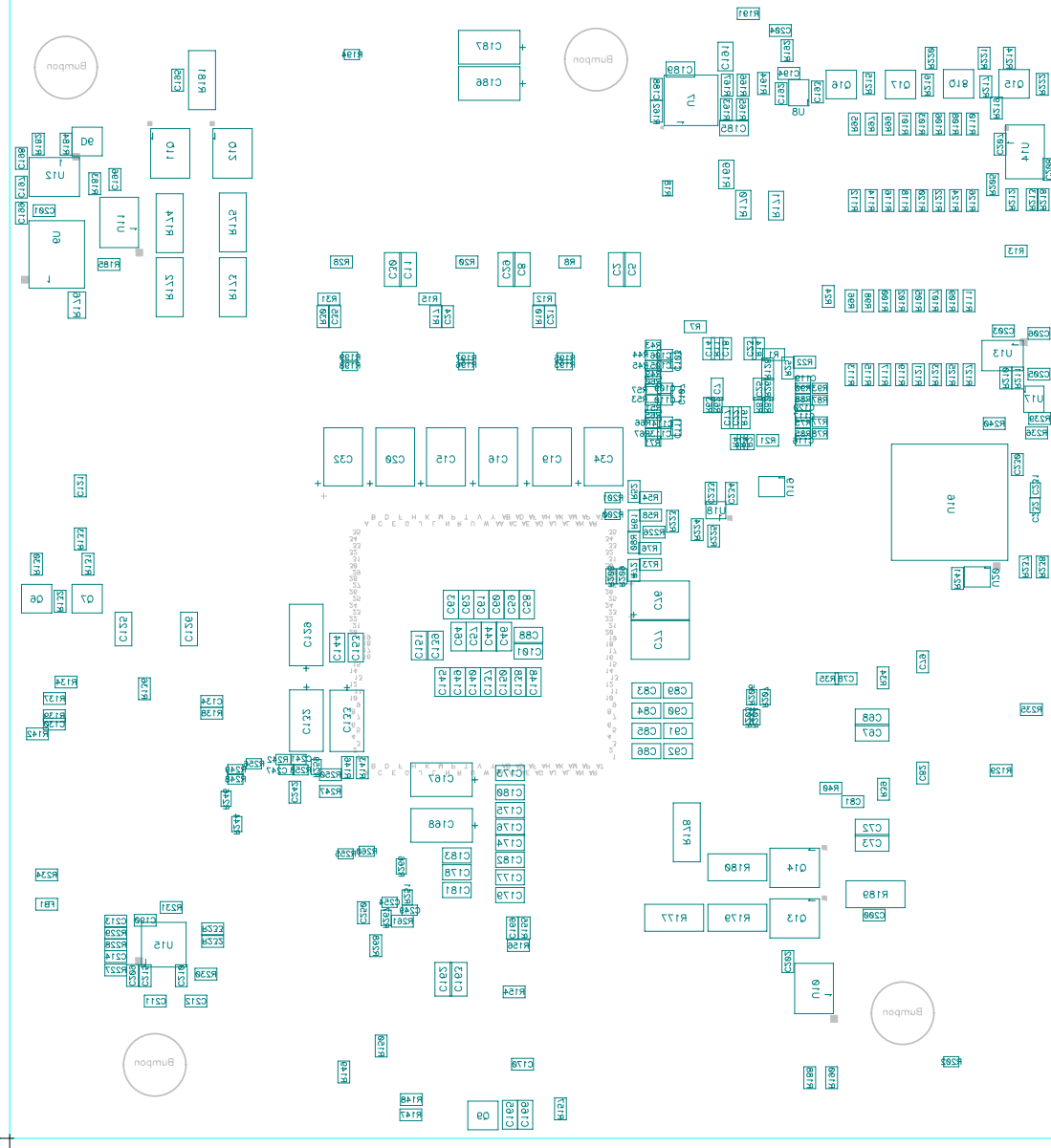
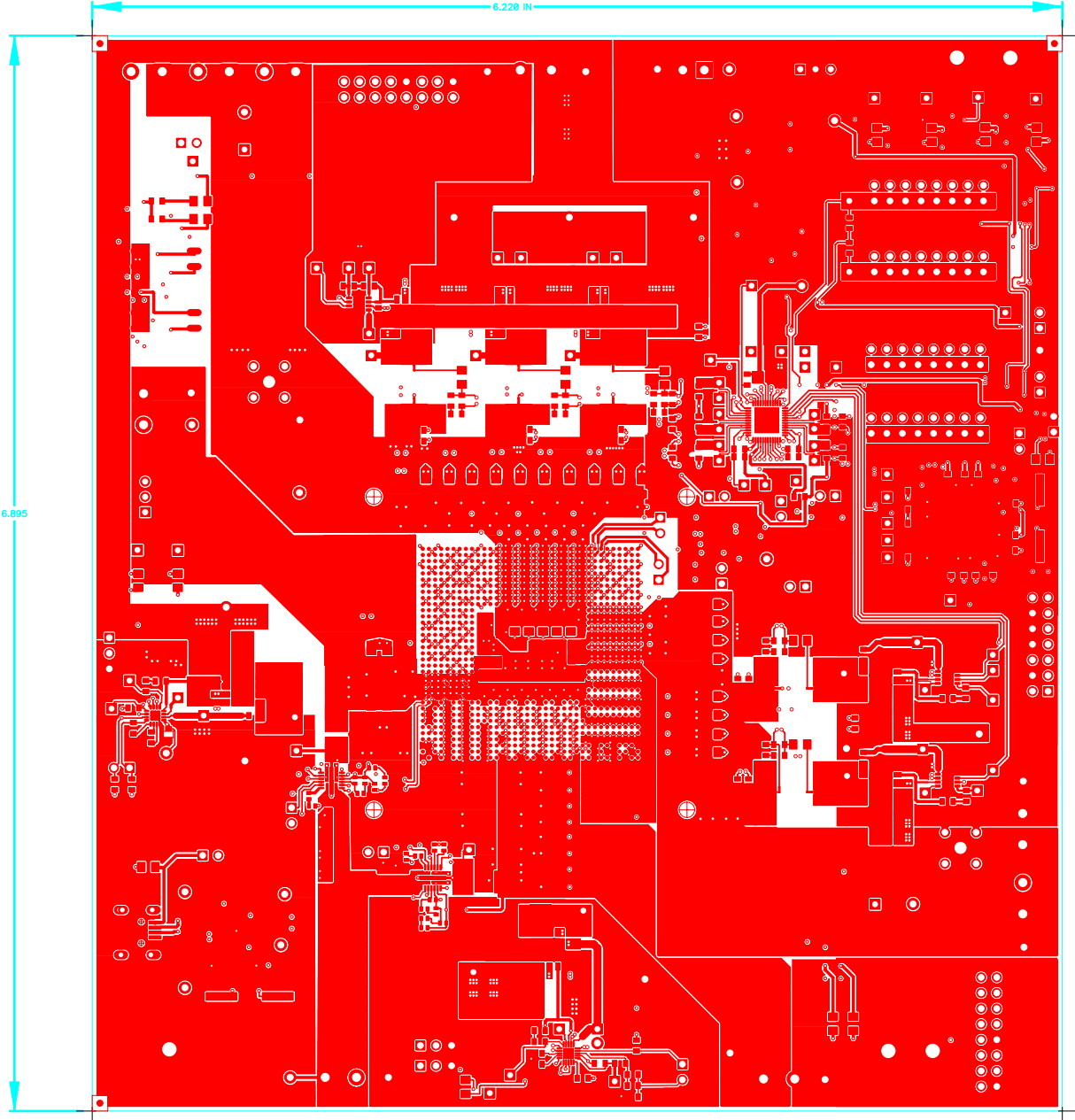


TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
Board No.	Rev.	Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
HPA753	A				S1				TA		
Date: 11/30/2010	Filename: HPA753A1.pcb	Engineer: Nancy Zhang	PCB Dwg: E. Archambault	Modified Date: Wed Jan 25, 2012	Time Stamp: 10:46:43						



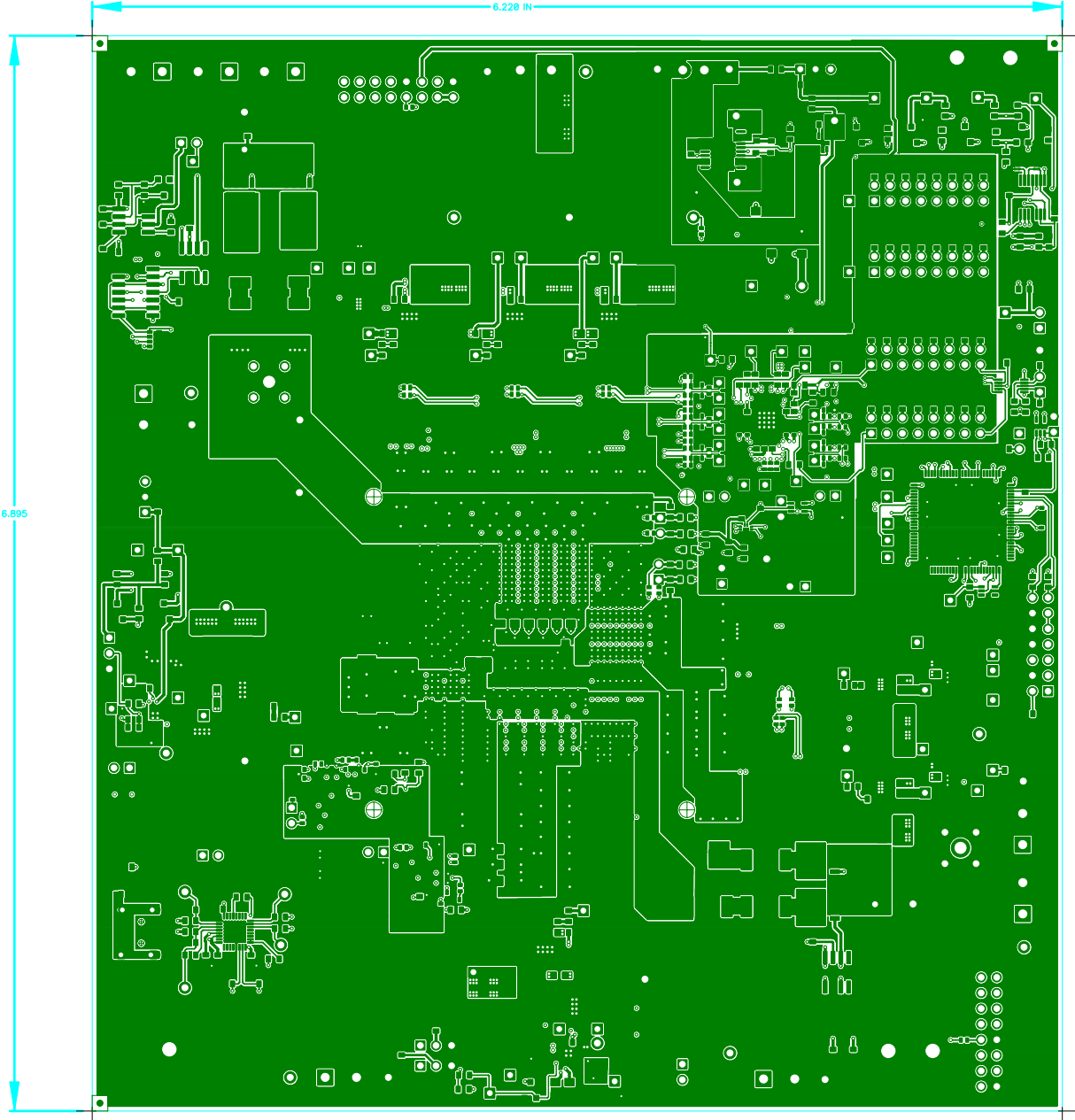
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA753	Rev.	A				S8			BA	
Date:	11/30/2010	Filename:	HPA753A1.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	E. Archambault	Modified Date:	Wed Jan 25, 2012	Time Stamp:	10:46:43



6.220 IN

6.695

TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA753	Rev.	A	L1								
Date:	11/30/2010	Filename:	HPA753A1.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	E. Archambault	Modified Date:	Wed Jan 25, 2012	Time Stamp:	10:46:44	



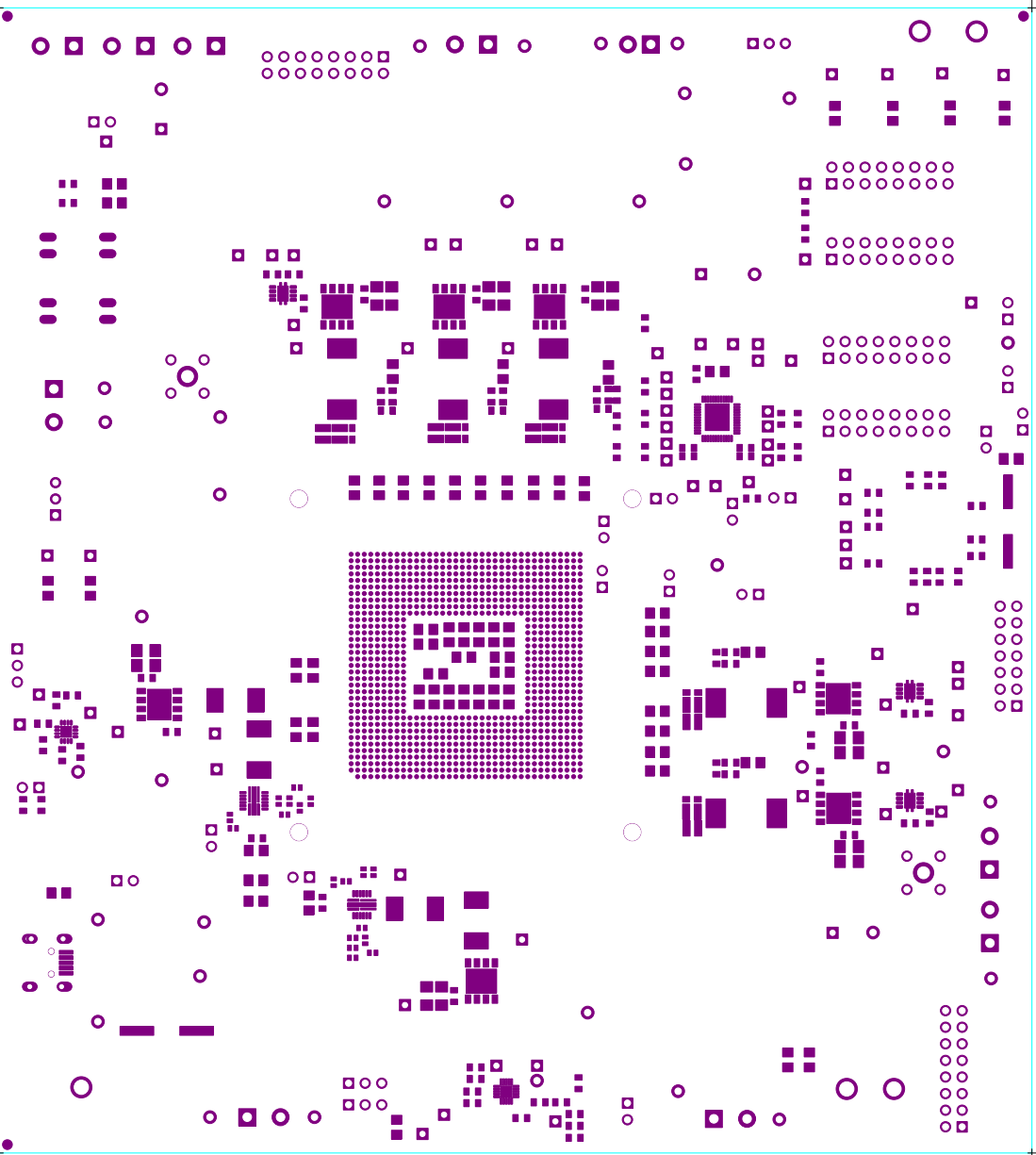
6.220 IN

6.695

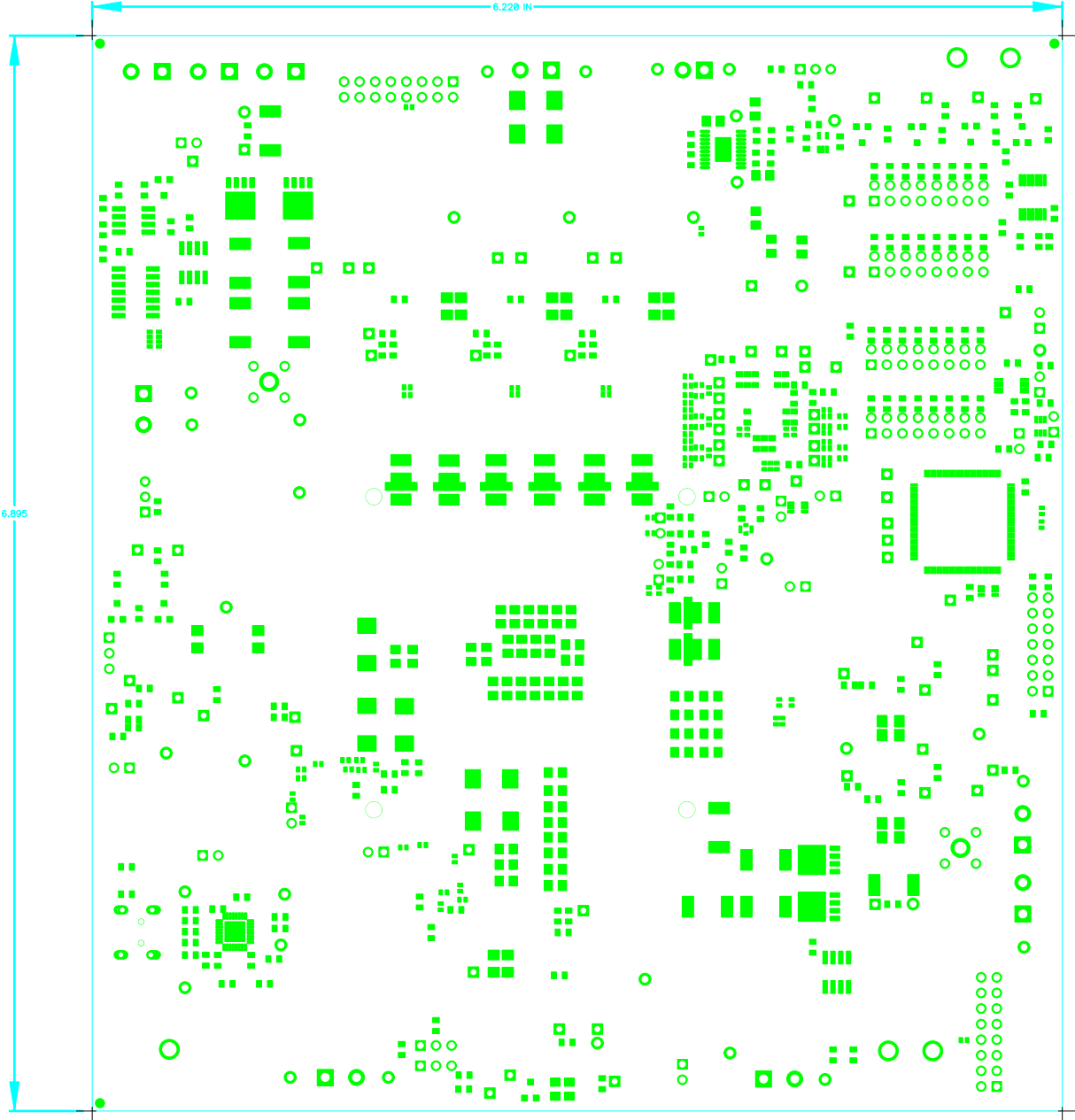
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No. HPA753	Rev. A			L8								
Date: 11/30/2010	Filename: HPA753A1.pcb	Engineer: Nancy Zhang	PCB Dgnr: E. Archambault	Modified Date: Wed Jan 25, 2012								Time Stamp: 10:46:46

6.220 IN

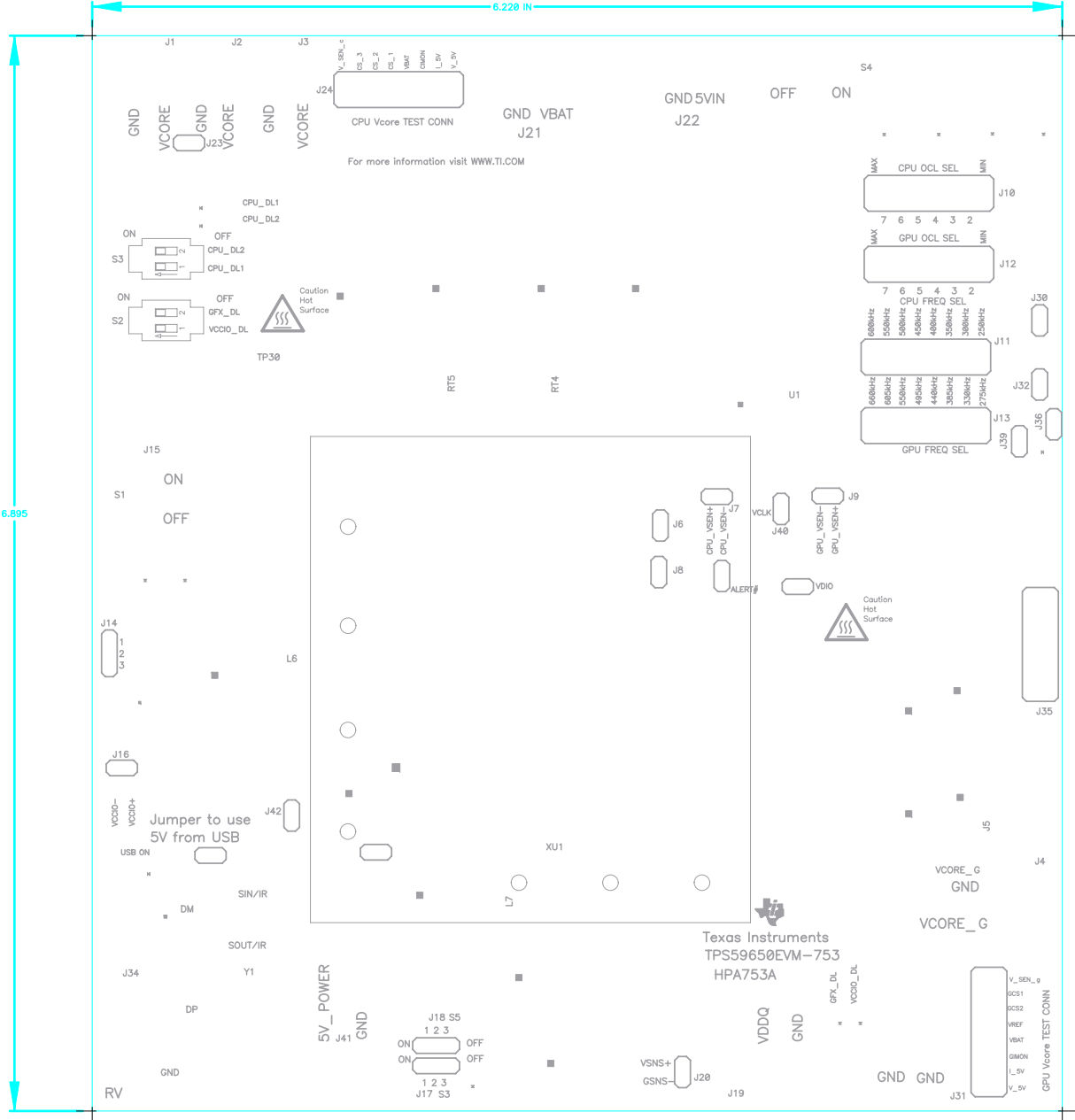
6.695



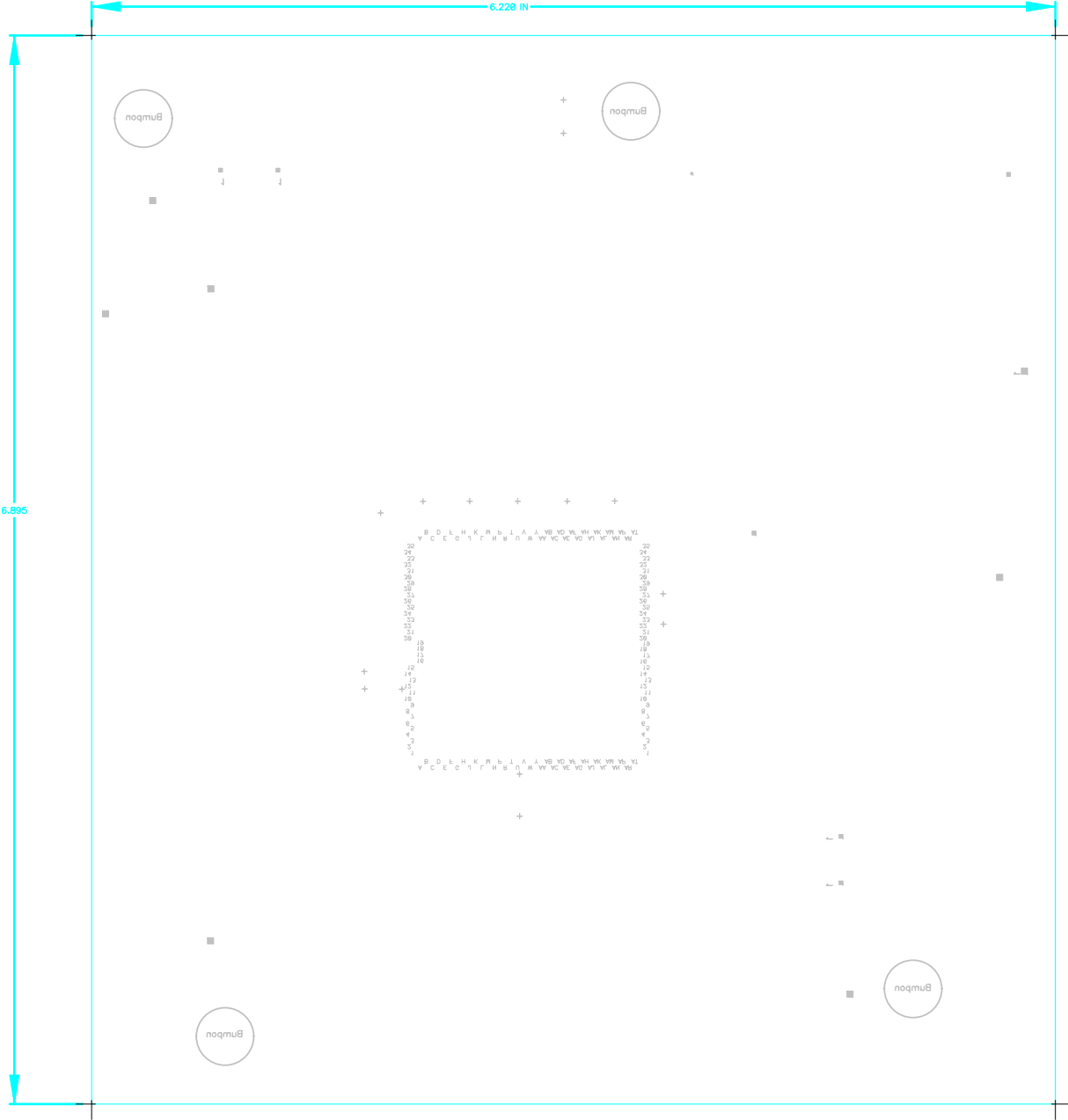
TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing	
		Top	Internal				Bot	Top	Bot	Top	Bot	Top	Bot		
Board No.	HPA753	Rev.	A												
Date:	11/30/2010	Filename:	HPA753A1.pcb		Engineer:	Nancy Zhang		PCB Designer:	E. Archambault		Modified Date:	Wed Jan 25, 2012		Time Stamp:	10:46:47



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing		
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot			
Board No.	HPA753	Rev.	A								M8			
Date:	11/30/2010	Filename:	HPA753A1.pcb		Engineer:	Nancy Zhang		PCB Dgnr:	E. Archambault		Modified Date:	Wed Jan 25, 2012	Time Stamp:	10:46:47



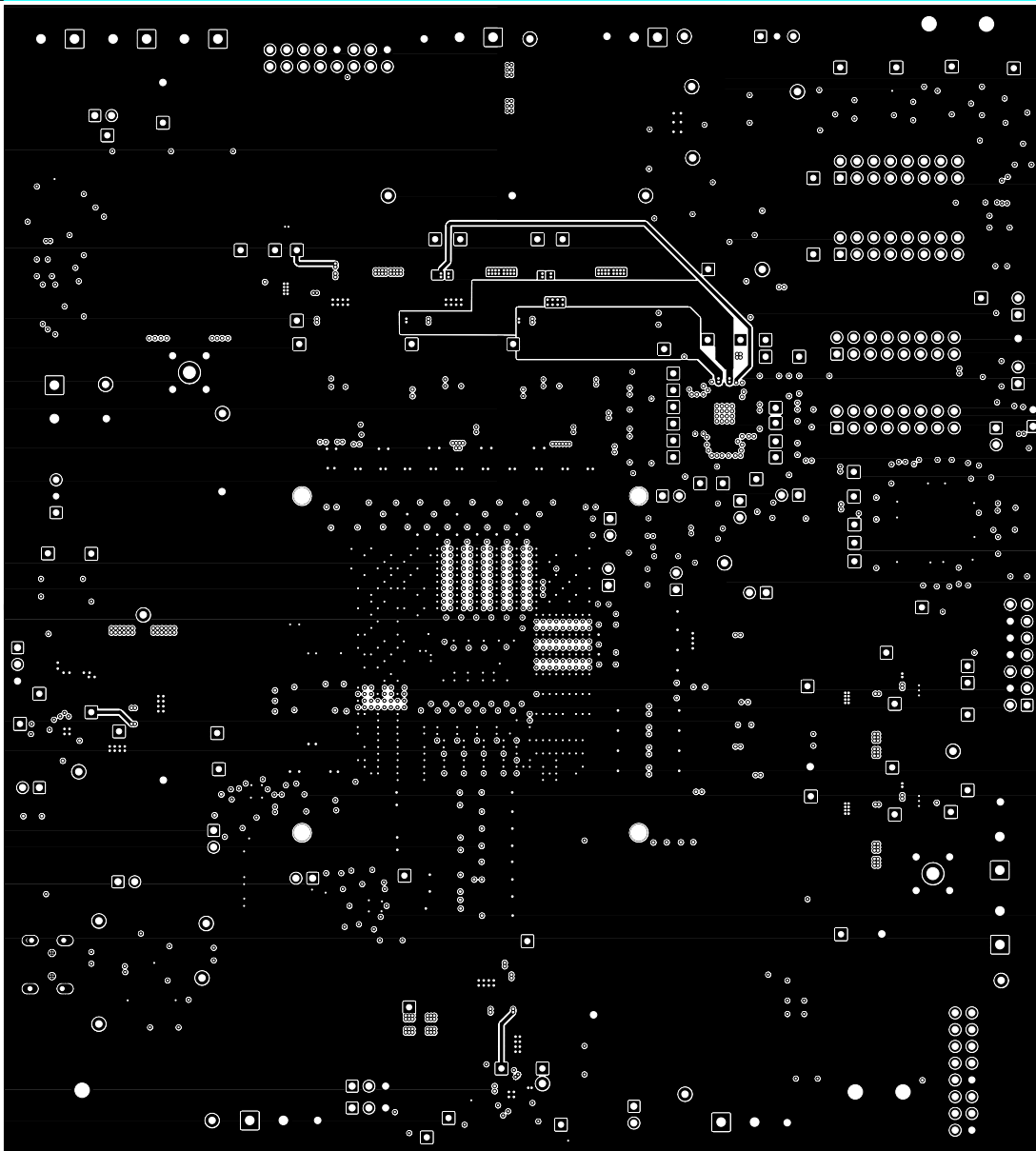
TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA753	Rev.	A				S1					
Date:	11/30/2010	Filename:	HPA753A1.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	E. Archambault	Modified Date:	Wed Jan 25, 2012	Time Stamp:	10:46:47	



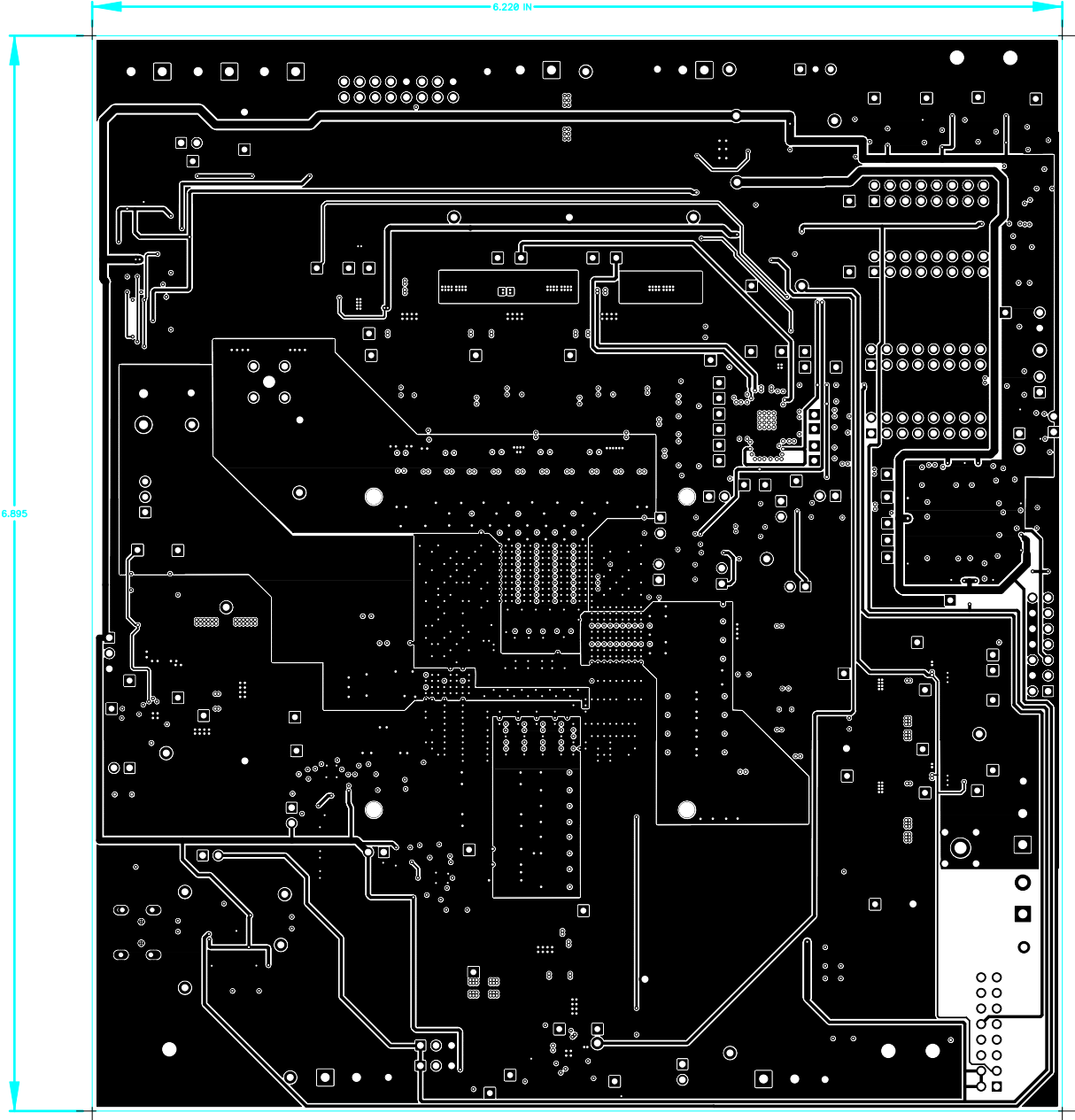
TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing	
		Top	Internal				Bot	Top	Bot	Top	Bot	Top	Bot		
Board No.	HPA753	Rev.	A						S8						
Date:	11/30/2010	Filename:	HPA753A1.pcb		Engineer:	Nancy Zhang		PCB Dgnr:	E. Archambault		Modified Date:	Wed Jan 25, 2012		Time Stamp:	10:46:48

5.220 IN

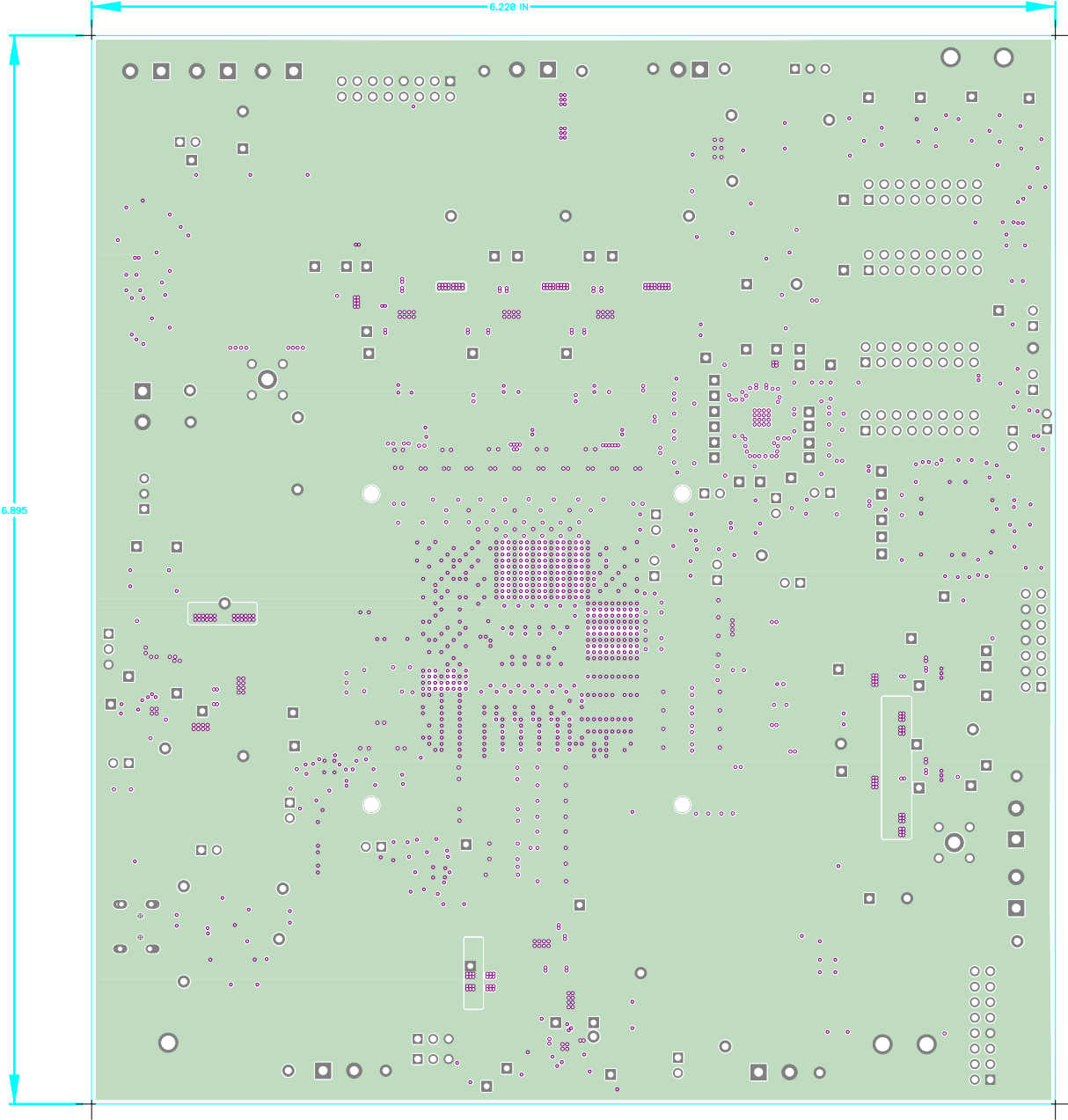
6.695



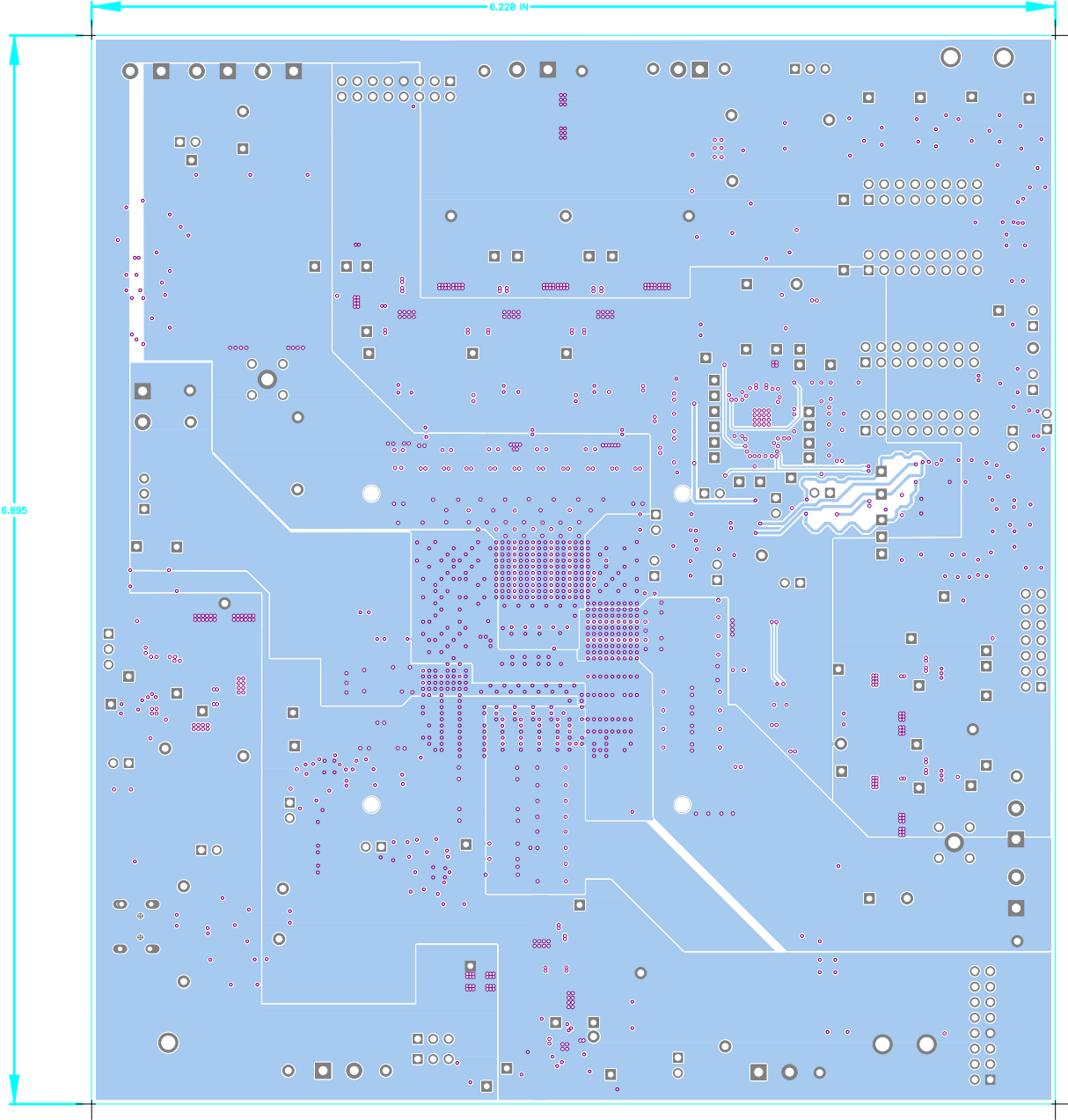
TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing	
		Top	Internal				Bot	Top	Bot	Top	Bot	Top	Bot		
Board No.	HPA753	Rev.	A		L2										
Date:	11/30/2010	Filename:	HPA753A1.pcb		Engineer:	Nancy Zhang		PCB Dgnr:	E. Archambault		Modified Date:	Wed Jan 25, 2012		Time Stamp:	10:46:48



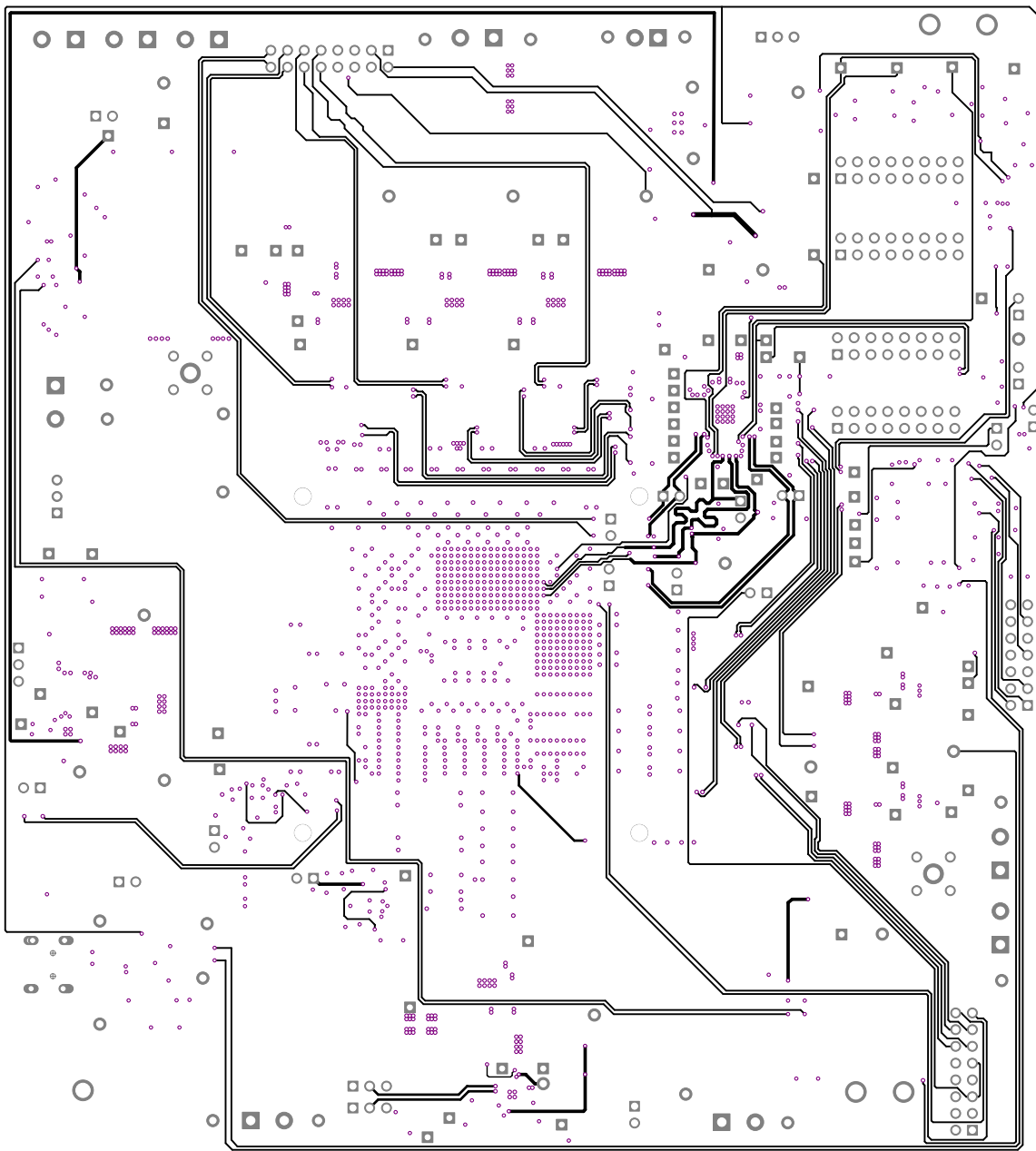
TEXAS INSTRUMENTS		Copper Layer Name			Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal	Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA753	Rev.	A	L3							
Date:	11/30/2010	Filename:	HPA753A1.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	E. Archambault	Modified Date:	Wed Jan 25, 2012	Time Stamp:	10:46:49

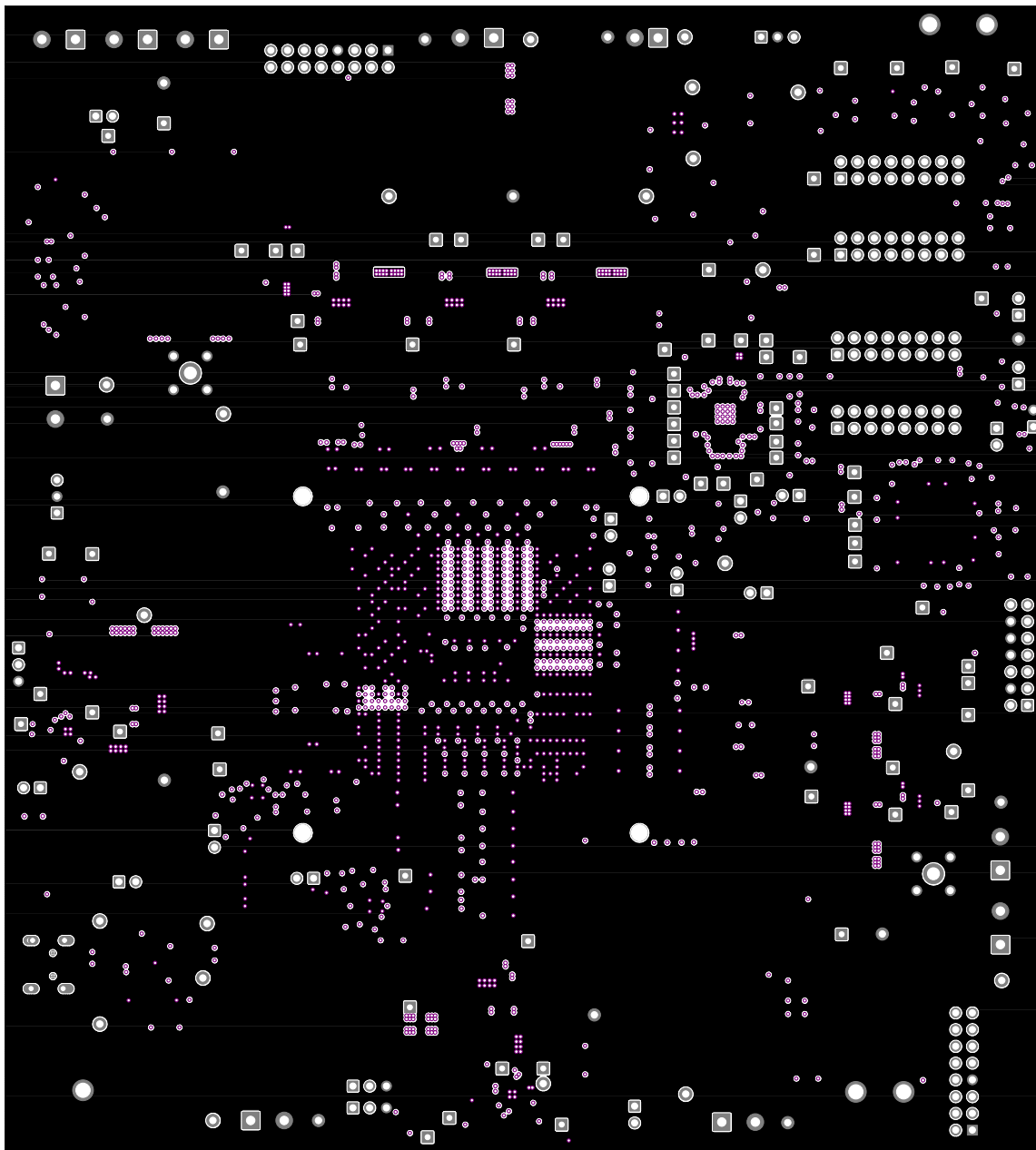


TEXAS INSTRUMENTS		Copper Layer Name						Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal				Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA753	Rev.	A			L4								
Date:	11/30/2010	Filename:	HPA753A1.pcb	Engineer:	Nancy Zhang	PCB Designer:	E. Archambault	Modified Date:	Wed Jan 25, 2012	Time Stamp:	10:46:50			



TEXAS INSTRUMENTS		Copper Layer Name				Silkscreen		Mask		Assembly		Fab Drawing
		Top	Internal		Bot	Top	Bot	Top	Bot	Top	Bot	
Board No.	HPA753	Rev.	A	L5								
Date:	11/30/2010	Filename:	HPA753A1.pcb	Engineer:	Nancy Zhang	PCB Dgnr:	E. Archambault	Modified Date:	Wed Jan 25, 2012	Time Stamp:	10:46:51	





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